



STPS8H100D/F/G/G-1

HIGH VOLTAGE POWER SCHOTTKY RECTIFIER

MAIN PRODUCT CHARACTERISTICS

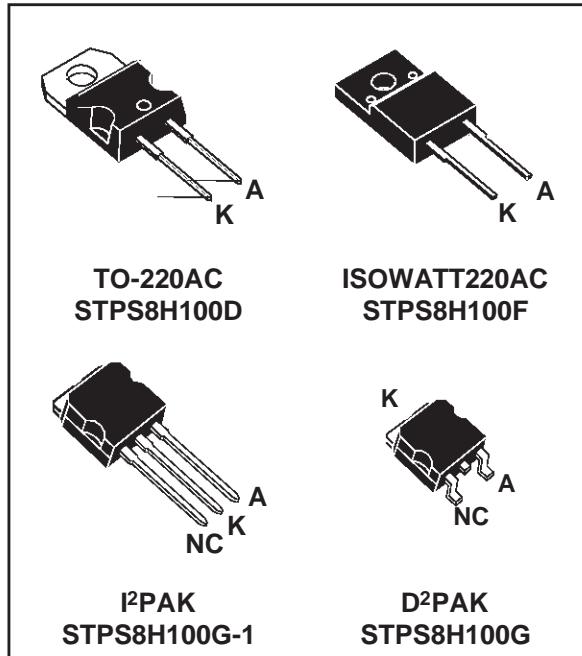
I _{F(AV)}	8 A
V _{RRM}	100 V
T _{j(max)}	175 °C
V _{F(max)}	0.58 V

FEATURES AND BENEFITS

- NEGLIGIBLE SWITCHING LOSSES
- HIGH JUNCTION TEMPERATURE CAPABILITY
- LOW LEAKAGE CURRENT
- GOOD TRADE OFF BETWEEN LEAKAGE CURRENT AND FORWARD VOLTAGE DROP
- AVALANCHE RATED

DESCRIPTION

Schottky barrier rectifier designed for high frequency compact Switched Mode Power Supplies such as adaptors and on board DC/DC converters.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			100	V
I _{F(RMS)}	RMS forward current			30	A
I _{F(AV)}	Average forward current δ = 0.5	TO-220AC / I ² PAK / D ² PAK	T _c = 165 °C	8	A
		ISOWATT220AC	T _c = 150 °C		
I _{FSM}	Surge non repetitive forward current	tp = 10 ms sinusoidal		250	A
I _{IRRM}	Repetitive peak reverse current	tp = 2 µs F = 1kHz square		1	A
I _{IRSM}	Non repetitive peak reverse current	tp = 100 µs square		3	A
E _{as}	Non repetitive avalanche energy	T _j = 25 °C I _{as} = 2 A	L = 60 mH	24	mJ
I _{ar}	Repetitive avalanche current	Va = 1.5 x V _R typ Current decaying linearly to 0 in 1 µs Frequency limited by T _j max.		2	A
T _{stg}	Storage temperature range	- 65 to + 175		°C	
T _j	Maximum operating junction temperature	175		°C	
dV/dt	Critical rate of rise of rise voltage	10000		V/µs	

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THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
R _{th} (j-c)	Junction to case	TO-220AC / I ² PAK / D ² PAK	1.6	°C/W
R _{th} (j-c)	Junction to case	ISOWATT220AC	4	°C/W

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
I _R *	Reverse leakage current	T _j = 25°C	V _R = V _{RRM}			4.5	μA
		T _j = 125°C			2	6	mA
V _F **	Forward voltage drop	T _j = 25°C	I _F = 8 A			0.71	V
		T _j = 25°C	I _F = 10 A			0.77	
		T _j = 25°C	I _F = 16 A			0.81	
		T _j = 125°C	I _F = 8 A		0.56	0.58	
		T _j = 125°C	I _F = 10 A		0.59	0.64	
		T _j = 125°C	I _F = 16 A		0.65	0.68	

Pulse test : * tp = 5 ms, δ < 2%

** tp = 380 μs, δ < 2%

To evaluate the maximum conduction losses use the following equation :

$$P = 0.48 \times I_{F(AV)} + 0.0125 \times I_{F}^2(RMS)$$

Fig. 1: Average forward power dissipation versus average forward current.
(TO-220AC / ISOWATT220AC / I²PAK / D²PAK)

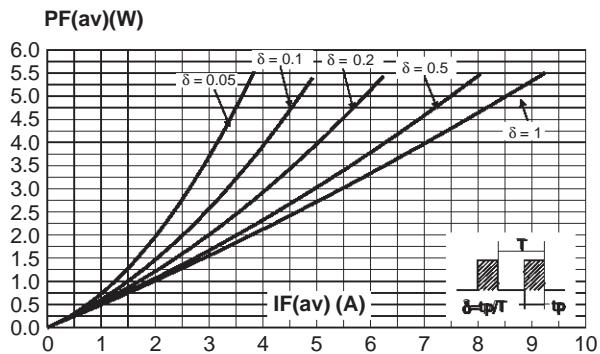


Fig. 2-1: Average forward current versus ambient temperature (δ=0.5) (TO-220AC / I²PAK / D²PAK).

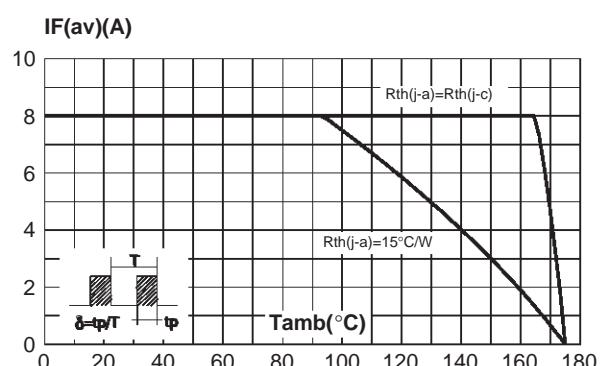


Fig. 2-2: Average forward current versus ambient temperature ($\delta=0.5$) (ISOWATT220AC).

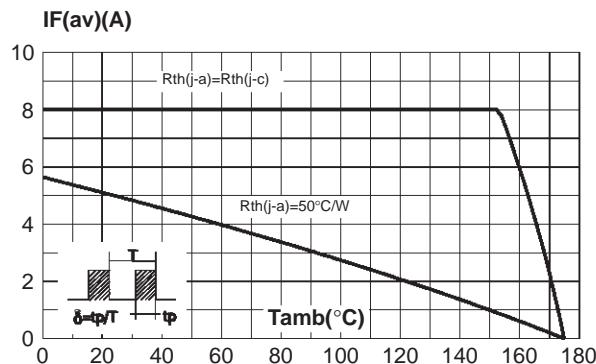


Fig. 3-2: Non repetitive surge peak forward current versus overload duration (maximum values) (ISOWATT220AC).

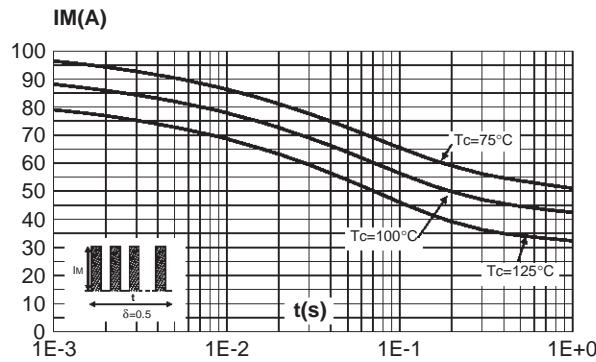


Fig. 4-2: Relative variation of thermal impedance junction to case versus pulse duration (ISOWATT220AC).

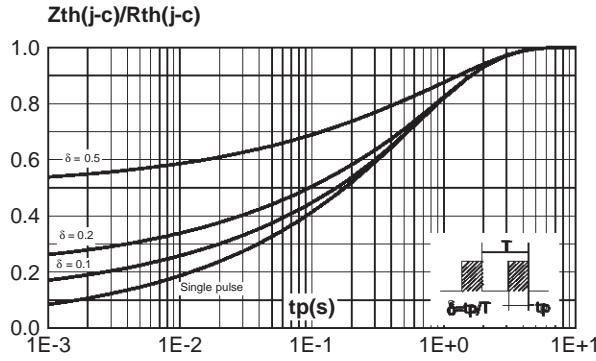


Fig. 3-1: Non repetitive surge peak forward current versus overload duration (maximum values) (TO-220AC / $I^2\text{PAK}$ / $D^2\text{PAK}$).

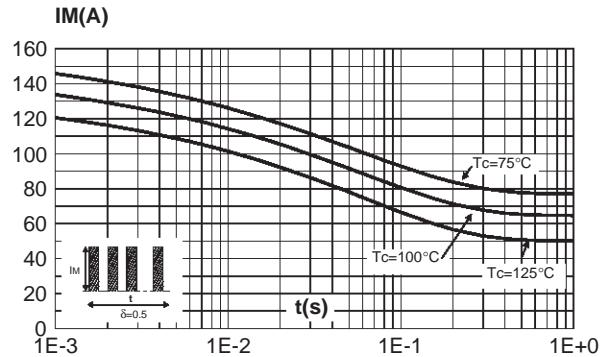


Fig. 4-1: Relative variation of thermal impedance junction to case versus pulse duration (TO-220AC / $I^2\text{PAK}$ / $D^2\text{PAK}$).

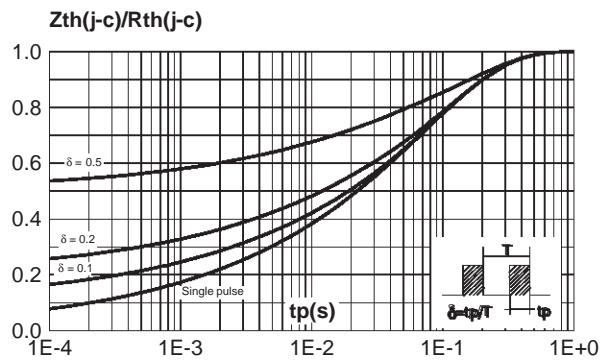
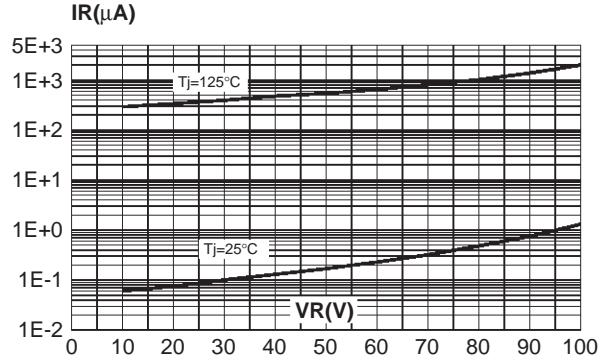


Fig. 5: Reverse leakage current versus reverse voltage applied (typical values).



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Fig. 6: Junction capacitance versus reverse voltage applied (typical values).

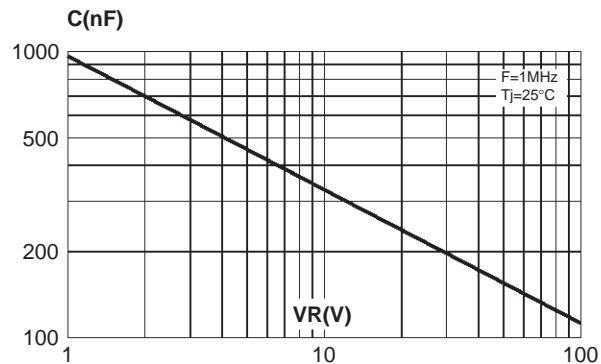


Fig. 7: Forward voltage drop versus forward current (maximum values).

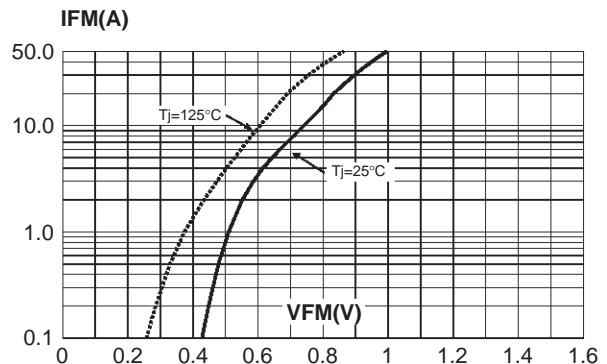
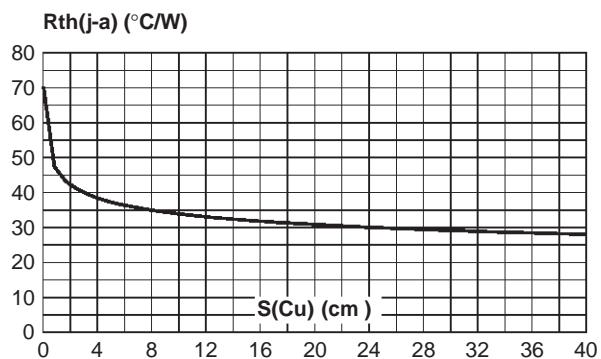
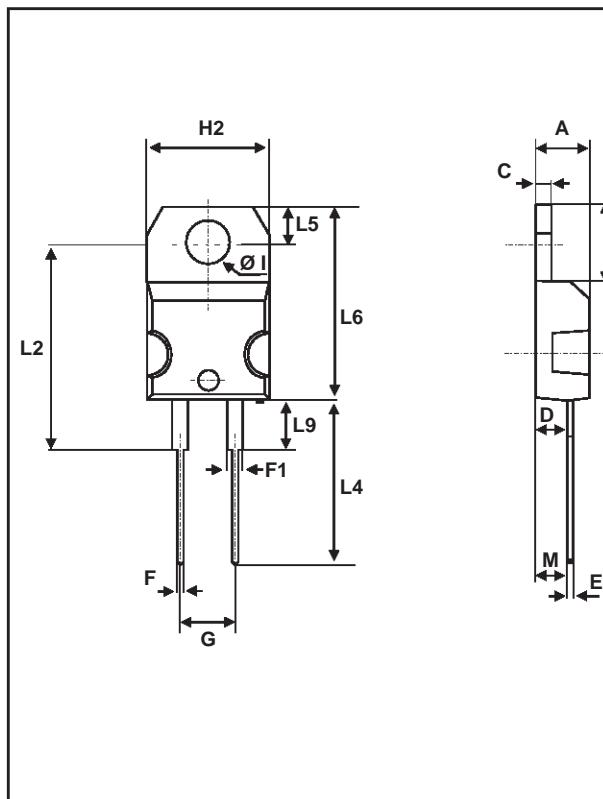


Fig. 8: Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness: 35 μm) (D^2PAK).

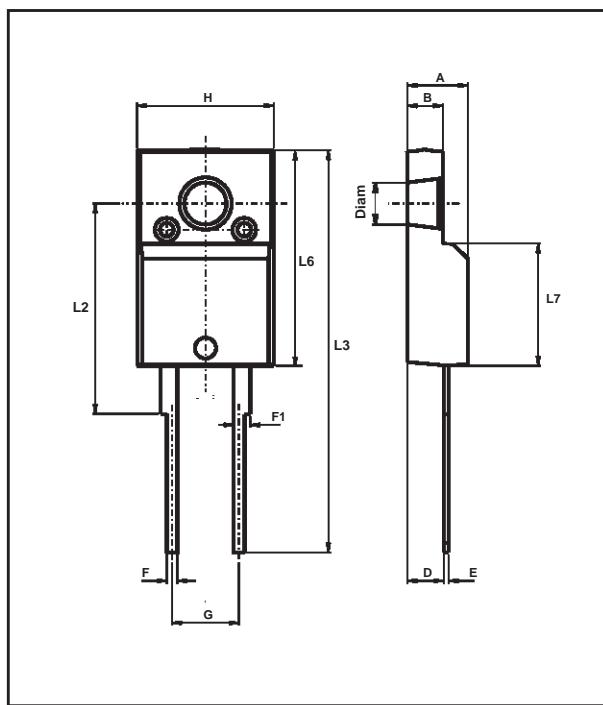


PACKAGE MECHANICAL DATA
TO-220AC

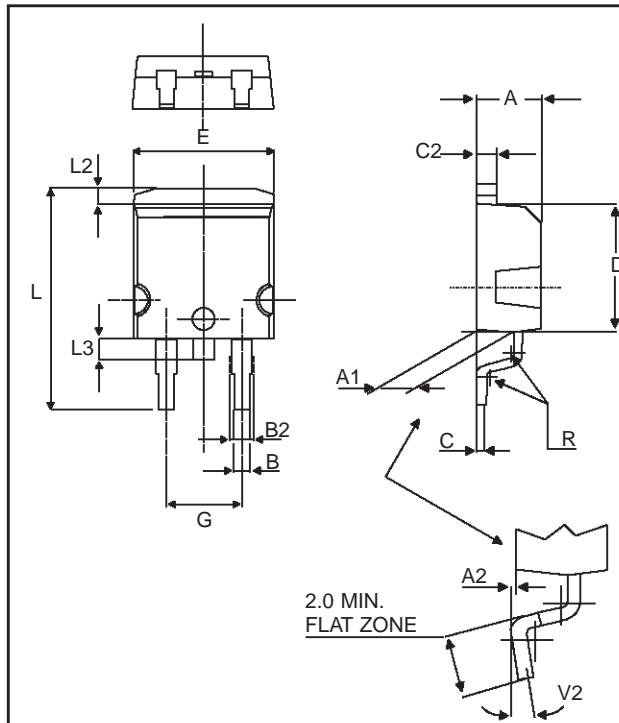


REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

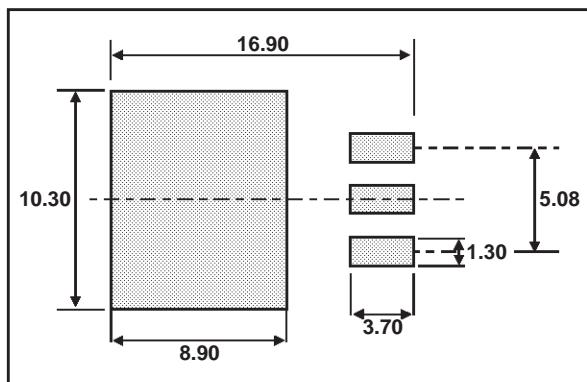
PACKAGE MECHANICAL DATA
ISOWATT220AC



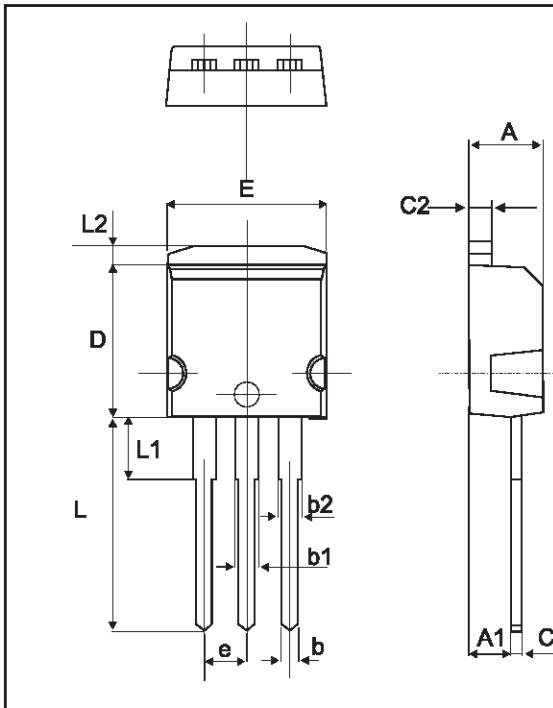
REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	2.50		2.70	0.098		0.106
D	2.40		2.75	0.094		0.108
E	0.40		0.70	0.016		0.028
F	0.75		1.00	0.030		0.039
F1	1.15		1.70	0.045		0.067
G	4.95		5.20	0.195		0.205
H	10.00		10.40	0.394		0.409
L2	16.00			0.630		
L3	28.60		30.60	1.125		1.205
L6	15.90		16.40	0.626		0.646
L7	9.00		9.30	0.354		0.366
Diam	3.00		3.20	0.118		0.126

STPS8H100D/F/G/G-1**PACKAGE MECHANICAL DATA**
D²PAK

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.30		4.60	0.169		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.70		0.93	0.027		0.037
B2		1.40			0.055	
C	0.45		0.60	0.017		0.024
C2	1.21		1.36	0.047		0.054
D	8.95		9.35	0.352		0.368
E	10.00		10.28	0.393		0.405
G	4.88		5.28	0.192		0.208
L	15.00		15.85	0.590		0.624
L2	1.27		1.40	0.050		0.055
L3	1.40		1.75	0.055		0.069
R		0.40			0.016	
V2	0°		8°	0°		8°

FOOTPRINT (in millimeters) D²PAK

PACKAGE MECHANICAL DATA
I²PAK



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.30		4.60	0.169		0.181
A1	2.49		2.69	0.098		0.106
b	0.70		0.93	0.028		0.037
b1	1.20		1.38	0.047		0.054
b2	1.25	1.40		0.049	0.055	
C	0.45		0.60	0.018		0.024
C2	1.21		1.36	0.048		0.054
D	8.95		9.35	0.352		0.368
e	2.44		2.64	0.096		0.104
E	10.00		10.28	0.394		0.405
L	13.10		13.60	0.516		0.535
L1	3.48		3.78	0.137		0.149
L2	1.27		1.40	0.050		0.055

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS8H100D	STPS8H100D	TO-220AC	1.86g	50	Tube
STPS8H100F	STPS8H100F	ISOWATT220AC	2.00g	50	Tube
STPS8H100G-1	STPS8H100G	I ² PAK	1.49g	50	Tube
STPS8H100G	STPS8H100G	D ² PAK	1.48g	50	Tube
STPS8H100G-TR	STPS8H100G	D ² PAK	1.48g	500	Tape & reel

■ Epoxy meets UL94,V0

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